

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1415	257/738.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 20:57
S2	373	S1 and resist	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 20:50
S3	18	S2 and (die adj pad)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 20:54
S4	38	S2 and (die near3 pad)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 20:54
S5	20	S4 not S3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 20:55
S6	1692	257/737.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 20:57
S7	468	S6 and resist	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 20:57
S8	37	S7 and (die near3 pad)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 20:58
S9	14	S8 not S4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 20:58

S10	14	S9 not S3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 21:01
S11	3	(die near3 pad) and ((external near3 (lead or terminal or electrode or solder)) same ((opening or void) near3 resist))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/04 15:41
S12	2875	257/758.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 20:46
S13	177	(semiconductor or die or ic or chip or (integrated adj circuit)) and (solder or brazing) and (plate or plating) and (die adj pad) and (bonding adj pad) and (resin or epoxy or encapsulant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 13:21
S14	630	257/782.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/15 17:21
S15	2117	257/778.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 14:52
S16	924	257/783.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 14:52
S17	1763	257/784.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 14:52
S18	419	257/772.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 14:53
S19	1415	257/738.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 14:53

S20	3353	257/787.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 14:53
S21	1482	257/700.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 14:53
S22	2875	257/758.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 14:53
S23	12321	257/782.ccls. or 257/778.ccls. or 257/783.ccls. or 257/784.ccls. or 257/772.ccls. or 257/738.ccls. or 257/787.ccls. or 257/700.ccls. or 257/758.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 14:54
S24	5461	(257/782.ccls. or 257/778.ccls. or 257/783.ccls. or 257/784.ccls. or 257/772.ccls. or 257/738.ccls. or 257/787.ccls. or 257/700.ccls. or 257/758.ccls.) and (solder or brazing or ag)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 14:54
S25	2761	((257/782.ccls. or 257/778.ccls. or 257/783.ccls. or 257/784.ccls. or 257/772.ccls. or 257/738.ccls. or 257/787.ccls. or 257/700.ccls. or 257/758.ccls.) and (solder or brazing or ag)) and (plate or plating)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 14:55
S26	4338	((257/782.ccls. or 257/778.ccls. or 257/783.ccls. or 257/784.ccls. or 257/772.ccls. or 257/738.ccls. or 257/787.ccls. or 257/700.ccls. or 257/758.ccls.) and (solder or brazing or ag)) and (bond or bonding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 14:56
S27	2301	((257/782.ccls. or 257/778.ccls. or 257/783.ccls. or 257/784.ccls. or 257/772.ccls. or 257/738.ccls. or 257/787.ccls. or 257/700.ccls. or 257/758.ccls.) and (solder or brazing or ag)) and (plate or plating)) and (bond or bonding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 14:56

S28	1893	(((257/782.ccls. or 257/778.ccls. or 257/783.ccls. or 257/784.ccls. or 257/772.ccls. or 257/738.ccls. or 257/787.ccls. or 257/700.ccls. or 257/758.ccls.) and (solder or brazing or ag)) and (plate or plating)) and (bond or bonding)) and (encapsulant or resin or epoxy)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 14:57
S29	1841	(((257/782.ccls. or 257/778.ccls. or 257/783.ccls. or 257/784.ccls. or 257/772.ccls. or 257/738.ccls. or 257/787.ccls. or 257/700.ccls. or 257/758.ccls.) and (solder or brazing or ag)) and (plate or plating)) and (bond or bonding)) and (encapsulant or resin or epoxy)) not ((semiconductor or die or ic or chip or (integrated adj circuit)) and (solder or brazing) and (plate or plating) and (die adj pad) and (bonding adj pad) and (resin or epoxy or encapsulant))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 14:59
S35	6586	(semiconductor or chip or die or ic or (integrated adj circuit)) and (die near3 pad) and (lead or terminal or electrode or solder or pad) and (resin or encapsulant or epoxy)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/04 15:45
S36	2850	"257"/\$6.ccls. and ((semiconductor or chip or die or ic or (integrated adj circuit)) and (die near3 pad) and (lead or terminal or electrode or solder or pad) and (resin or encapsulant or epoxy))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/04 16:30
S37	1698	"257"/\$6.ccls. and ((semiconductor or chip or die or ic or (integrated adj circuit)) and (die near3 pad) and (lead or terminal or electrode or solder or pad) and (resin or encapsulant or epoxy))	USPAT	OR	OFF	2005/05/05 12:41
S38	52	"257"/\$6.ccls. and ((semiconductor or chip or die or ic or (integrated adj circuit)) and (die near3 pad) and (lead or terminal or electrode or solder or pad) and (resin or encapsulant or epoxy) and dummy)	USPAT	OR	OFF	2005/05/04 16:29

S39	88	"257"/\$6.ccls. and ((semiconductor or chip or die or ic or (integrated adj circuit)) and (die near3 pad) and (lead or terminal or electrode or solder or pad) and (resin or encapsulant or epoxy) and dummy)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/04 16:30
S40	1	("6501162").PN.	USPAT	OR	OFF	2005/05/05 12:36
S41	351	"257"/\$6.ccls. and ((semiconductor or chip or die or ic or (integrated adj circuit)) and (die near3 pad) and (lead or terminal or electrode or solder or pad) and (resin or encapsulant or epoxy))	EPO; JPO; DERWENT	OR	OFF	2005/05/05 12:41
S42	1	"6459549".PN.	USPAT; USOCR	OR	OFF	2005/05/05 12:53
S43	1	"6001671".PN.	USPAT; USOCR	OR	OFF	2005/05/05 12:53
S44	772	257/782.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/15 17:29
S45	1	("6646331").PN.	USPAT	OR	OFF	2005/12/15 17:29
S46	1	("6975022").PN.	USPAT	OR	OFF	2005/12/15 17:30
S47	1	("6501162").PN.	USPAT	OR	OFF	2005/12/15 17:30
S48	1	("6963126").PN.	USPAT	OR	OFF	2005/12/15 17:30
S49	1	("6624511").PN.	USPAT	OR	OFF	2005/12/15 17:31
S50	1	("6548328").PN.	USPAT	OR	OFF	2005/12/15 17:32
S51	1	("6562660").PN.	USPAT	OR	OFF	2005/12/15 17:32
S52	1	("6545364").PN.	USPAT	OR	OFF	2005/12/15 20:25
S53	649	(semiconductor or ic or chip or die or (integrated adj circuit)) and (die adj pad) and ((bond or bonding) near2 pad) and (plated or plating)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/15 21:50
S54	585	S53 and (encapsulant or encapsulating or encapsulated or resin or epoxy)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/15 21:51



S55	64	S53 not S54	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/15 21:42
S56	0	"E23." "031".ccds.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/15 21:43
S57	3	"E23.031"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/15 21:43
S58	0	"E23.032"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/15 21:43
S59	1	"E23.033"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/15 21:44
S60	1	"E23.034"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/15 21:44
S61	1	"E23.037"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/15 21:44
S62	1	"E23.038"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/15 21:44

S63	0	"E23.004"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/15 21:44
S64	1	"E23.04"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/15 21:44
S65	3	"E23.066"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/15 21:44
S66	2	"E23.068"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/15 21:44
S67	0	"E23.003"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/15 21:44
S68	0	"E23.01"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/15 21:44
S69	3	"E23.015"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/15 21:44
S70	2	"E23.02"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/15 21:44

S71	0	"E23.023"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/15 21:45
S72	0	"E23.026"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/15 21:45
S73	15	S56 S57 S58 S59 S60 S61 S62 S63 S64 S65 S66 S67 S68 S69 S70	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/15 21:45
S74	1753	(semiconductor or ic or chip or die or (integrated adj circuit)) and (die adj pad) and ((bond or bonding) near2 pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/15 21:51
S75	2927	(semiconductor or ic or chip or die or (integrated adj circuit)) and (die adj pad) and ((bond or bonding) near2 pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 23:17
S76	2278	S75 not S53	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 21:51
S77	1564	S76 and (encapsulant or encapsulating or encapsulated or resin or epoxy)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/15 23:00
S78	714	S76 not S77	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/15 23:00



S79	702	(semiconductor or ic or chip or die or (integrated adj circuit)) and (die adj paddle) and ((bond or bonding) near2 pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 23:17
S80	723	(semiconductor or ic or chip or die or (integrated adj circuit)) and (die adj paddle) and ((bond or bonding) near2 (pad or paddle))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 23:17
S81	621	S80 not S75	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 23:17